

DELIVERING *FASTER* BROADBAND, FURTHER...



mBOND® FLEX DATA SHEET

mBond® Flex is the first telecoms scalable solution providing fast-broadband pipes over existing copper lines using vendor agnostic xDSL bonding over VDSL2 and ADSL2+. By using existing copper the cost effective **mBond Flex** delivers an immediately deployable solution with both low operational barriers to deployment and a fast return on investment. **mBond**

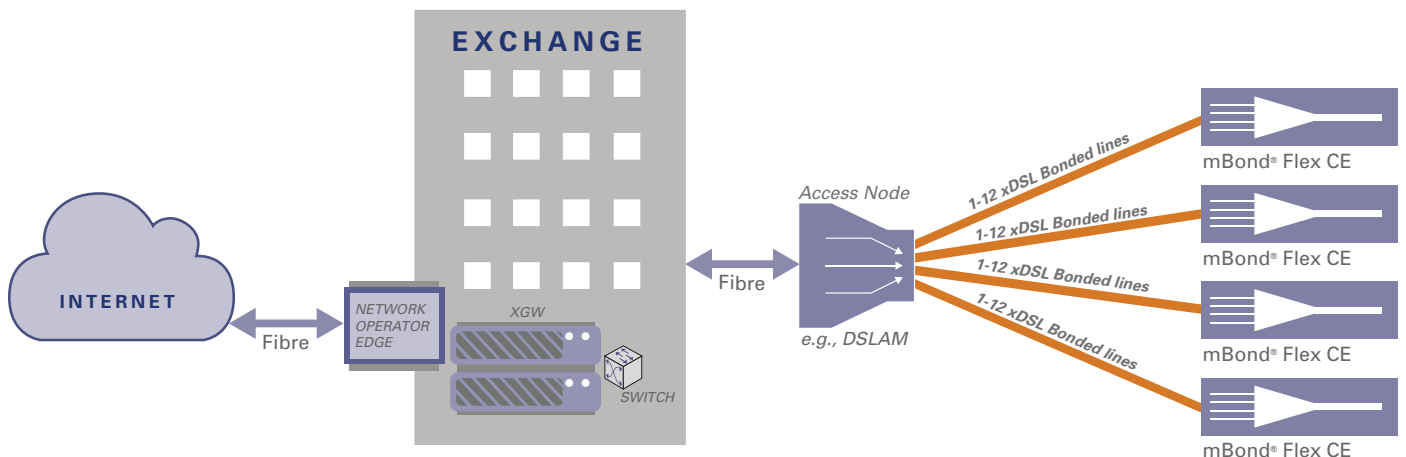
Flex has two components, a standard Intel based server at the Central Office or Exchange and a 1U rack mountable Customer Equipment (CE) device, at the customer site supporting up to twelve bonded xDSL lines. Multiple CE devices can be supported up to the throughput limits of the server and the desired contention limits of the operator.

HIGHLIGHTS

- Low operational barriers to deployment, uses existing copper
- Industry first vendor agnostic xDSL bonding platform
- Standard Intel/Redhat based server architecture at the Exchange
- Scalable per customer with operator defined contention limits from no contention to 20:1
- Support for VDSL2 and ADSL2+
- Small 1RU CE device footprint in cabinet / at customer site
- High Density, up to twelve xDSL circuits per CE device
- Ideal solution for business broadband access, multi-dwelling units and mobile data backhaul, including small cell backhaul

KEY FACTS

- Software Exchange Gateway (XGW)
- DSLAM vendor agnostic
- Intel & Linux based
- Customer CE device
- 3 x RJ45 interfaces, 12 xDSL lines
- VDSL2 and ADSL2+ compatible
- 1 RU height



AN AFFORDABLE, FLEXIBLE SOLUTION

Over the last ten years carriers globally have embarked on multiple programs to increase broadband access speeds to their customers. In many cases these increased speeds have been delivered by fibre optic networks, either directly to the premise or to a local hub where local services are then delivered either by more fibre, radio or the existing copper infrastructure. However, in many cases pushing fibre out to the extremities of a carrier's network can be extremely expensive and in some cases impossible. **mBond Flex** has been created to work with the customer's existing fibre/copper networks to deliver incremental bandwidth today, at a small fraction of the cost of extending the fibre network.

mBond Flex is an extensible, vendor agnostic way of leveraging existing copper to bond xDSL links and use existing copper to meet the fast-broadband challenge. Multiple **mBond Flex** CE devices are supported, to the limit of the Server throughput capacity, with flexible contention ratios from 1:1 to 20:1.

mBond Flex delivers cost effective and immediate fast-broadband to business customers out of reach of fibre or where over-the-air solutions are unviable. **mBond Flex** supports business scale deployment for enterprises, multi-dwelling devices, mobile data backhaul and small cell architectures.

mBond Flex uses an industry standard Intel server at the Exchange or Head End to support multiple **mBond Flex** CE devices, which have have both CLI and WebUI management with SNMPv2 monitoring.

TECHNICAL DETAILS

mBOND FLEX EXCHANGE GATEWAY

Server Specifications

- Genuine Intel 8 Core Processor, (or 2 x 4 Core)
- Dual Port Genuine Intel 1Gb NIC card
- 16GB RAM
- 2 x 250Gb HD (Min) in RAID 1 (Mirrored) configuration

Operating System

- Redhat Server Enterprise

mBOND FLEX CE DEVICE

Operations and Management

- CLI provides secure configuration and diagnostics, accessed via the Ethernet RJ45 management port
- SNMP V2c RO supported over IPv4
- Web UI management interface accessed via standard web browser

Indicators

- Traffic Status LED
- Management Port LED
- Power LED
- 12 x xDSL Status LEDs

Power, Temperature and Weight

- DC Power, 1A @ -48V
- Input Range 36V – 72V, (40W typical)
- Dual -48V feeds
- Temp, Operational – 0C to 50C
- Temp, Storage - -25C to 70C
- Weight, 3KG
- Size, 1RU

Compliance

- RoHS Directive 2011/65/EU
- IEC 60950-1-2005+A1:2009
- EN60950-1:2006/A12:2011
- IECEE CB scheme certified

EMC

- FCC 47CFR 2010, Part 15 subpart (b) (Class A)
- ETSI EN 300-386:V1.5.1
- EN 55022:2010
- EN 61000-4-2, EN 61000-4-3, EN 61000-4-4, EN 61000-4-5, EN 61000-4-6, EN 61000-4-11

Canada

Suite 909, 825 - 8th Avenue S.W.
Calgary, Alberta
T2P 2T3
Canada
Tel: +1 403 266-5895

United Kingdom

The Venture Centre, University of Warwick Science Park
Sir William Lyons Road, Coventry, CV4 7EZ
United Kingdom
Tel: +44 24 7632 3334

